507501764 09/20/2022

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YUEH CHUN CHENG	09/20/2022

RECEIVING PARTY DATA

Name:	AMBARELLA INTERNATIONAL LP	
Street Address:	3101 JAY STREET	
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State/Country:	CALIFORNIA	
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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17948910

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NAME OF SUBMITTER:	ROBERT MILLER
SIGNATURE:	/Robert M. Miller/
DATE SIGNED:	09/20/2022

Total Attachments: 1

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PATENT 507501764 REEL: 061156 FRAME: 0442

ASSIGNMENT

In exchange for good and valuable consideration, the receipt of which is hereby acknowledged, I, Yueh Chun Cheng, hereby sell, assign and transfer to Ambarella International LP, a Canadian limited partnership, (hereinafter referred to as "ASSIGNEE"), having a place of business at 3101 Jay Street, Santa Clara, CA, 95054, the full and exclusive right title and interest in and to any and all improvements disclosed in the attached application for United States Patent entitled "LC-TANK-BASED PHASE-LOCKED LOOP (LCPLL)", any and all divisions, reissues, continuations, substitutions, reexaminations, renewals and foreign equivalents thereof, all rights of priority resulting from the filing of said attached application, and any and all Letters Patents which issue from said attached application, together with all claims for damages by reason of past infringement of said patent and with the right to sue for and collect the same;

I hereby authorize and request the Officials of the United States Patent and Trademark Office and of any and all foreign Patent Offices to issue and all of said Letters Patents, when granted, to said ASSIGNEE as the assignee of our entire right, title and interest in and to the same, for the sole use of said ASSIGNEE, its successors and assigns, to the full end of the term for which said Letters Patents may be granted;

On request, I agree to execute all oaths, declarations, assignments, powers of attorney and other papers related to said attached application and any and all divisions, reissues, continuations, substitutions, reexaminations, renewals and foreign equivalents thereof; communicate to said ASSIGNEE, its successors, assigns and representatives all facts known to me concerning said improvements and the history thereof; and generally do everything possible to assist and aid said ASSIGNEE in obtaining, securing and maintaining patent protection for said improvements and for vesting title to said improvements and any and all applications for and patents on said improvements in said ASSIGNEE, its successors and assigns; and

I have made no previous assignment, grant, mortgage, license or other agreement to or with others affecting the rights and property conveyed herein.

Signature of Inventor

Date: 09/20/2022

Yueh Chun Cheng Name of Inventor

> PATENT REEL: 061156 FRAME: 0443

RECORDED: 09/20/2022